DISCRETE SEMICONDUCTORS

DATA SHEET



1N4148; 1N4448 High-speed diodes

Product specification Supersedes data of 1999 May 25 2002 Jan 23





High-speed diodes

1N4148; 1N4448

FEATURES

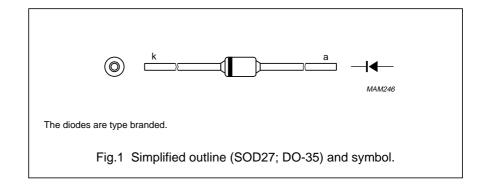
- Hermetically sealed leaded glass SOD27 (DO-35) package
- High switching speed: max. 4 ns
- · General application
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 100 V
- Repetitive peak forward current: max. 450 mA.

APPLICATIONS

· High-speed switching.

DESCRIPTION

The 1N4148 and 1N4448 are high-speed switching diodes fabricated in planar technology, and encapsulated in hermetically sealed leaded glass SOD27 (DO-35) packages.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		_	100	V
V _R	continuous reverse voltage		_	75	V
I _F	continuous forward current	see Fig.2; note 1	_	200	mA
I _{FRM}	repetitive peak forward current		_	450	mA
I _{FSM}	non-repetitive peak forward current	square wave; T _j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	_	4	Α
		t = 1 ms	_	1	Α
		t = 1 s	_	0.5	Α
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	500	mW
T _{stg}	storage temperature		-65	+200	°C
T _i	junction temperature		_	200	°C

Note

1. Device mounted on an FR4 printed circuit-board; lead length 10 mm.

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ELECTRICAL CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _F	forward voltage	see Fig.3			
	1N4148	I _F = 10 mA	_	1	V
	1N4448	$I_F = 5 \text{ mA}$	0.62	0.72	V
		I _F = 100 mA	_	1	V
I _R	reverse current	V _R = 20 V; see Fig.5		25	nA
		$V_R = 20 \text{ V; } T_j = 150 ^{\circ}\text{C; see Fig.5}$	_	50	μΑ
I _R	reverse current; 1N4448	$V_R = 20 \text{ V}; T_j = 100 ^{\circ}\text{C}; \text{ see Fig.5}$	_	3	μΑ
C _d	diode capacitance	f = 1 MHz; V _R = 0; see Fig.6	_	4	pF
t _{rr}	reverse recovery time	when switched from I_F = 10 mA to I_R = 60 mA; R_L = 100 Ω ; measured at I_R = 1 mA; see Fig.7	_	4	ns
V _{fr}	forward recovery voltage	when switched from $I_F = 50$ mA; $t_r = 20$ ns; see Fig.8	_	2.5	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point	lead length 10 mm	240	K/W
R _{th j-a}	thermal resistance from junction to ambient	lead length 10 mm; note 1	350	K/W

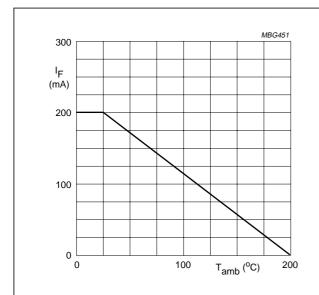
Note

1. Device mounted on a printed circuit-board without metallization pad.

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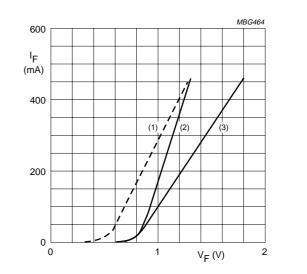
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GRAPHICAL DATA



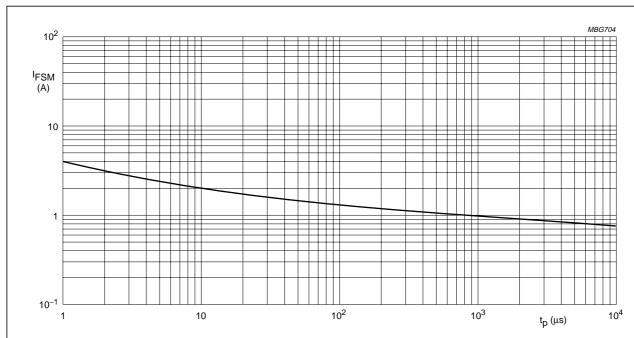
Device mounted on an FR4 printed-circuit board; lead length 10 mm.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



- (1) $T_j = 175$ °C; typical values.
- (2) $T_j = 25$ °C; typical values.
- (3) $T_j = 25$ °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



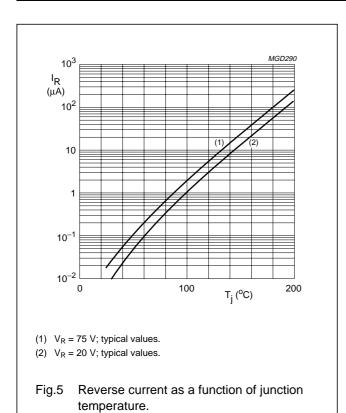
Based on square wave currents.

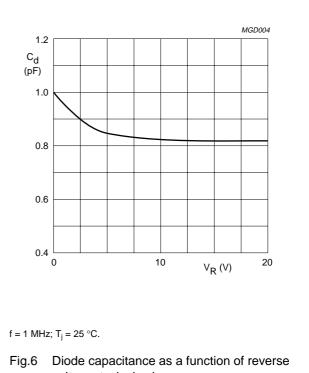
 $T_j = 25$ °C prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

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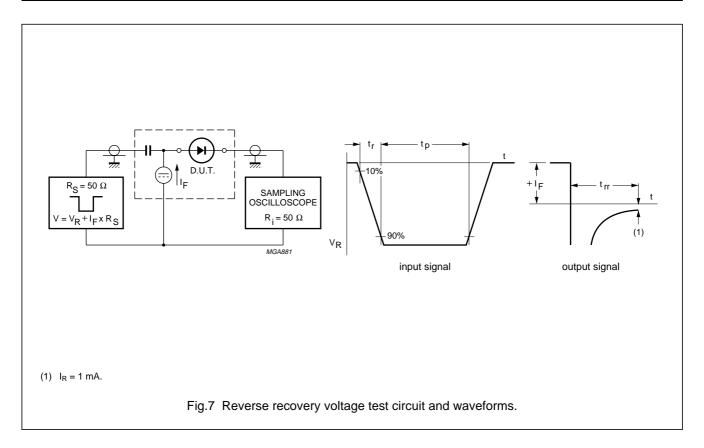


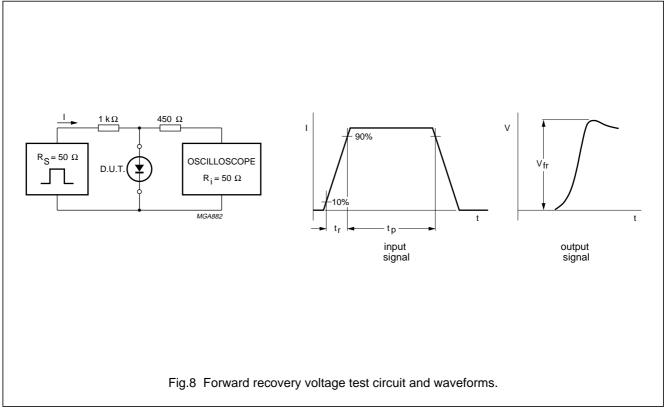
voltage; typical values.

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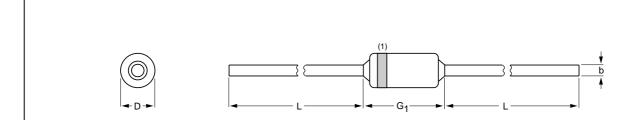
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PACKAGE OUTLINE

Hermetically sealed glass package; axial leaded; 2 leads

SOD27



DIMENSIONS (mm are the original dimensions)

UNIT	b max.	D max.	G ₁ max.	L min.	
mm	0.56	1.85	4.25	25.4	

0 1 2 mm

Note

1. The marking band indicates the cathode.

OUTLINE	REFERENCES			EUROPEAN	ICCUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOD27	A24	DO-35	SC-40			97-06-09

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DATA SHEET STATUS

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NOTES

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Contact information

For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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